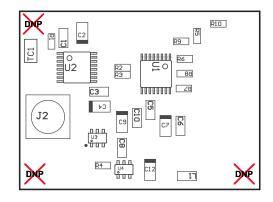
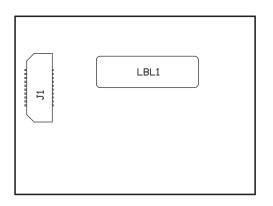
ZZI Install label in silkscreened box after final wash. Text shall be 8 pt font. Text shall be per the Label Table in the PDF schematic.

- ZZ2 These assemblies are ESD sensitive, ESD precautions shall be observed.
- ZZ3 These assemblies must be clean and free from flux and all contaminants. Use of no clean flux is not acceptable.
- ZZ4 ■These assemblies must comply with workmanship standards IPC-A-610 Class 2, unless otherwise specified.



COMPONENTS MARKED 'DNP' SHOULD NOT BE POPULATED. ASSEMBLY VARIANT: 001

PCB VIEWED FROM TOP SIDE	BOARD #: TIDA-00561	REV: E1	SVN REV:	: Not In VersionControl
IGNORE ->				
PLOT NAME = Top Assembly Drawing	GENERATED : 6/17/2	2015 9:10:01	AM	TEXAS INSTRUMENTS



COMPONENTS MARKED 'DNP' SHOULD NOT BE POPULATED. ASSEMBLY VARIANT: 001

PCB VIEWED FROM BOTTOM SIDE	BOARD #: TIDA-00561	REV: E1	SVN REV:	Not In VersionControl		
	IGNORE ->					
PLOT NAME = Bottom Assembly Drawing	GENERATED : 6/17/2	2015 9:10:02	AM	TEXAS INSTRUMENTS		

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